# Semiconductor Detectors (Solid State Detectors)

energy, position particles & photons



energy loss

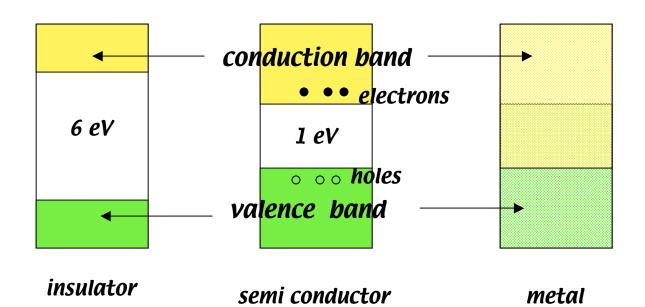


conversion electron-hole pairs



energetic "cheap" improved resolution

### Semiconductor Detectors (Solid State Detectors)



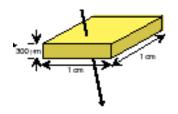
$$n_i = \sqrt{N_c N_v} \exp \left[ \frac{1}{2kT} \right] = AT^{3/2} \exp \left[ \frac{1}{2kT} \right]$$

 $N_{C,v}$ number of states conduction, valence band  $E_{g}$  Agap at 0 K

constant independent from T

for pure Si:  $n_i = 1.45 \times 10^{10}$  cm<sup>-3</sup>

# Semiconductor Detectors how to get a signal?



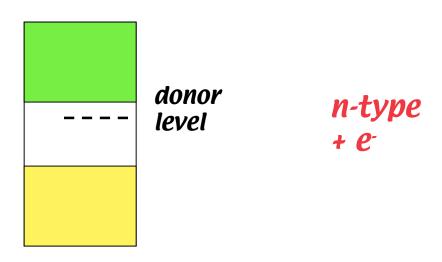
particle passing through a thin layer of Si: 300 ∏m

mimimum ionizing particle will produce: about 3.2x10<sup>4</sup> e-h pairs

but 4.5x108 free charge carriers in the same volume!

reduce number of free charge carriers, i.e. deplete material!

### Semiconductor Detectors "doped" n-type

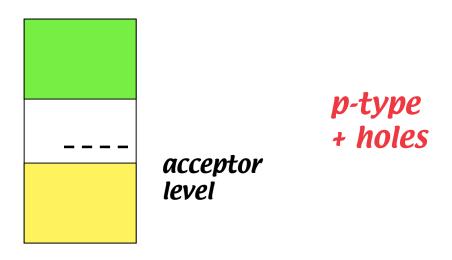


add donor elements: Vth group elements like P, As, Sb

extra electrons resides at discrete energy level in the energy gap, close to the CB (separated 0.01 - 0.05 eV)

conductivity enhanced by electrons
=> n-type semiconductors

# Semiconductor Detectors "doped" p-type



add acceptor elements: IIIrd group elements like Ga, B, In

extra electron states close to the VB, electrons easily excited into these states, creating hole states in the VB.

conductivity enhanced by holes states
=> p-type semiconductors

### Semiconductor Detectors "doped"

Typical doping levels for detector silicon:

10<sup>12</sup> atoms/cm<sup>-3</sup>

which has to be compared with  $10^{22}$  atoms/cm<sup>-3</sup> density Ge & Si

heavily doped semiconductors: ("+" sign after the material)

10<sup>20</sup> atoms/cm<sup>-3</sup>

band gap: Eg = 1.12 V.

E(e-hole pair) = 3.6 eV (~30 eV for gas detectors)

high specific density (2.33 g/cm³)

□E/track length for M.I.P.'s.: 390 eV/mm, ~108 e-h/ □m (average)

high mobility  $m_e = 1450 \text{ cm}^2/\text{Vs}$ ,  $m_h = 450 \text{ cm}^2/\text{Vs}$ 

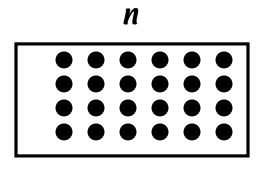
small dimensions fast charge collection (<10 ns)

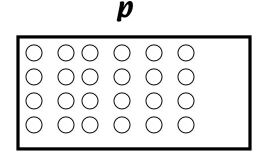
rigidity of silicon thin self supporting structures typical thickness 300 ☐m ~3.2 x10<sup>4</sup> e-h (average)

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### Semiconductor Detectors "np-junction"





n	p

initial diffusion:
holes -> n-region, electrons -> p-region

charge building up: n-region-> positive, p-region -> negative

emerging electric field (contact potential) stops diffusion

region of changing potential: depletion zone, space charge region

# Semiconductor Detectors increasing depletion

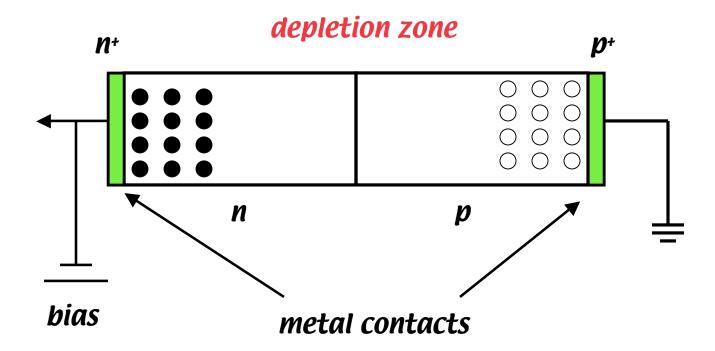
### depletion zone



reversed bias junction
(bias voltage about 100 V)
apply negative voltage to p-side
-> attract holes
apply positive voltage to n-side
-> attract electrons

-> increase depletion zone

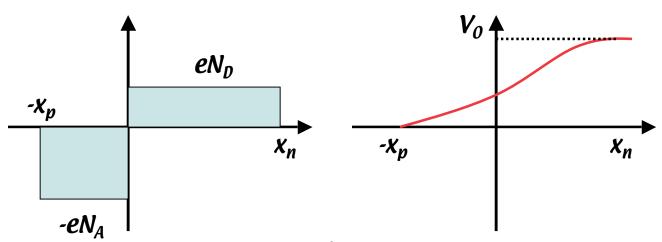
# Semiconductor Detectors signal read out



to prevent depletion zone between metal and semi conductor

-> layer of highly doped material

### depletion depth



**Poissons's equation:**  $\frac{d^2V}{dx^2} = \prod \frac{D(x)}{D}$ 

charge conservation :  $N_A x_p = N_D x_n$ 

depletion depth d

integration yields V(x):

$$0 < x < x_n$$

$$V(x) = \left[ \frac{eN_D}{D} \right] \frac{x^2}{2} \left[ x_n x \right] + C$$

$$\prod x_p < x < 0$$

$$V(x) = \frac{eN_A}{\Box} \boxed{x^2 \Box x_p x} + C'$$

matching at  $x = 0 \Rightarrow$ 

$$C = C'$$

$$C = \frac{eN_A}{2\Pi} x_p^2$$

#### depletion depth d

integration yields contact potential  $V(x_n)=V_0$ :

$$V_0 = \frac{e}{2D} \left( N_D x_n^2 + N_A x_p^2 \right)$$

and

$$x_{n} = \sqrt{\frac{2[N_{0}]}{eN_{D}(1+N_{D}/N_{A})}}$$

$$x_p = \sqrt{\frac{2[V_0]}{eN_A(1+N_A/N_D)}}$$

depletion zone extends farther into the lighter-doped side

depletion depth d

under assumption  $N_A >> N_D$ :

$$d = x_n + x_p \, \prod_{n \in \mathbb{N}_D} \frac{2 [N_0]}{e N_D}$$

resistivity of n-type material:

$$\square_n \square \frac{1}{eN_D\square_e}$$

 $\prod_e$  electron mobility  $[cm^2/Vs]$ 

$$d \left[ \sqrt{2 \prod_n \prod_e V_0} \right]$$

# Semiconductor Detectors characteristics "an application"

Assume  $\square = 20 \text{ k}\square$  cm for heavily doped n-type Si and  $V_0 = 100 \text{ V}$ . The dielectric constant  $\square / \square_0 = 12$  and  $\square_e (300\text{K}) = 1350 \text{ cm}^2/\text{Vs}$ .

How thick is the depletion zone?

junction capacitance

for planar geometry:

$$C = \Box \frac{A}{d}$$

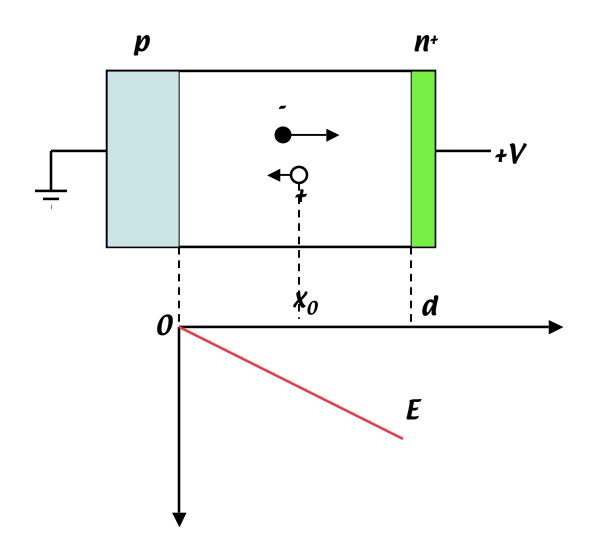
for  $N_D >> N_A$  or  $N_A >> N_D$ , respectively Si:

$$C/A = \frac{2.2}{\sqrt{\int_N V_0}} pF/mm^2 \qquad \text{n-type}$$

$$C/A = \frac{3.7}{\sqrt{\int_N V_0}} pF/mm^2 \qquad p - type$$

pulse shape, rise time charge collection time

for planar geometry, heavily doped p-type



pulse shape, rise time charge collection time

for planar geometry, heavily doped p-type:

$$dQ = \frac{qdx}{d}$$

integration of Poisson's equation:

$$\frac{dV}{dx} = E = \prod \frac{eN_A}{\prod} x = \prod \frac{x}{\prod_h \prod}$$

$$\square = \square\square$$
 with  $1/\square = eN_A\square_h$ 

$$v_e = \frac{dx_e}{dt} = \prod_e E = \frac{\int_e x}{\int_h x}$$

### if mobility independent of E

$$x_{e}(t) = x_{0} \exp \left[ \frac{\prod_{e} t}{\prod_{h} \prod_{e} t} \right]$$

#### electron reaches eletrode at x = d:

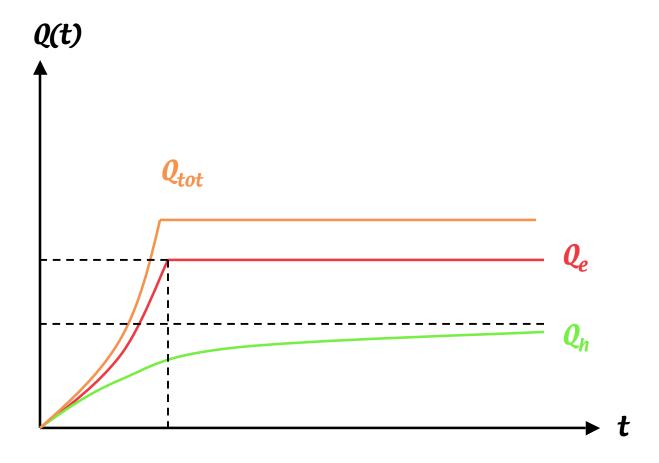
$$t = \prod_{h=1}^{n} \ln \frac{d}{x_0}$$

$$Q_{e}(t) = \left[ \frac{e}{d} \right] \frac{dx}{dt} dt = \frac{e}{d} x_{0} \left[ \frac{1}{d} \right] \left[ \exp \frac{\prod_{e} t}{\prod_{h} t} \right]$$

### analogue for holes, with

$$v_{h} = \square_{h} E = \square \frac{x}{\square}$$

$$Q_h(t) = \left[ \frac{e}{d} x_0 \right] \left[ \exp \frac{\Box t}{\Box} \right]$$



# Semiconductor Detectors characteristics "an application"

Estimate the rise time of the solid state detector discussed above !